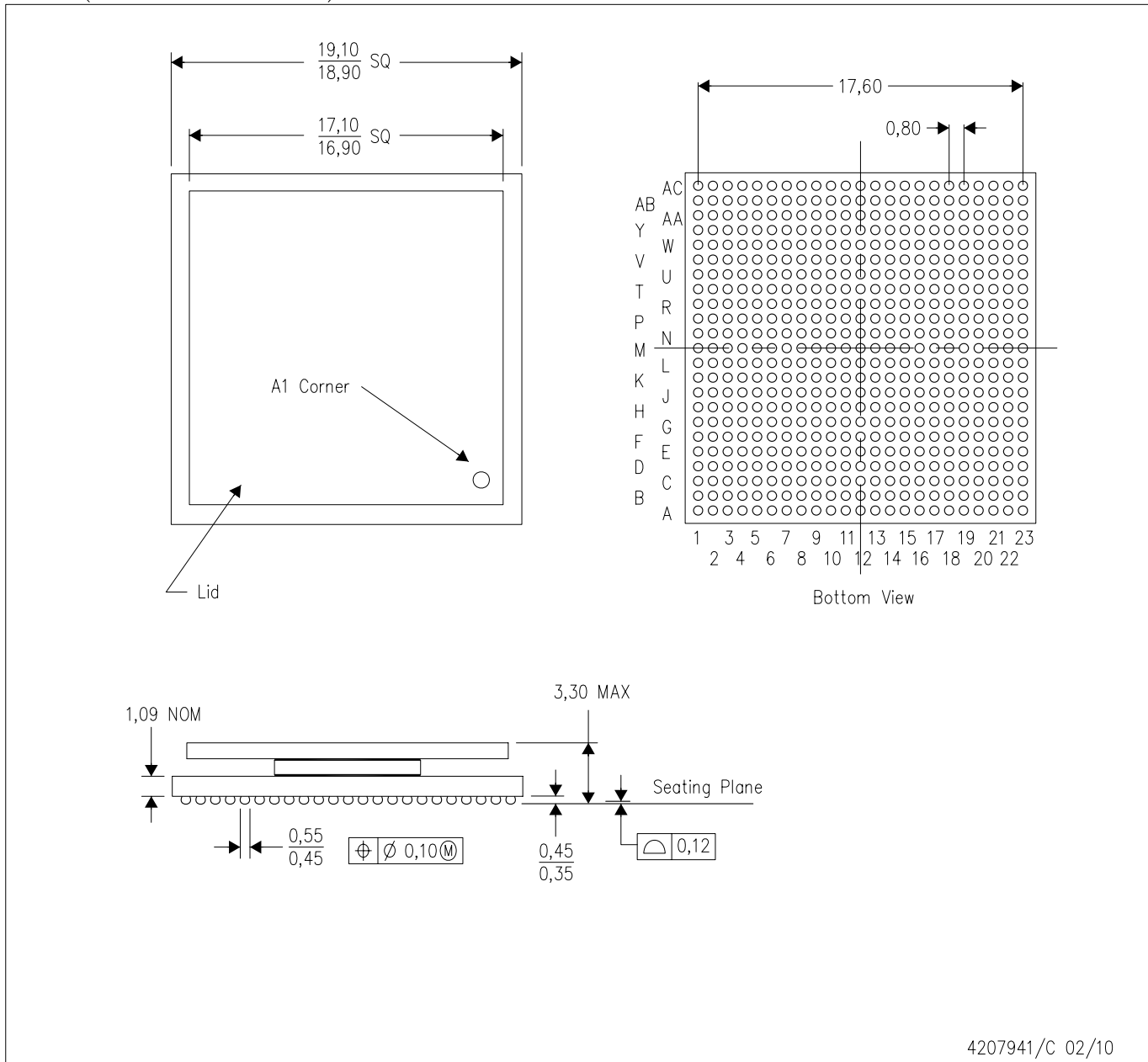


MECHANICAL DATA

ZUT (S-PBGA-N529)

PLASTIC BALL GRID ARRAY



4207941/C 02/10

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Thermally enhanced package with lid.
 - Flip chip application only.
 - This is a Pb-free solder ball design.

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